

IN THE CLAIMS

Please amend the claims as follows.

Please cancel claims 16-27 without prejudice.

1. (Previously Presented) An integrated circuit comprising:
 - at least one circuit element;
 - a node coupled to the at least one circuit element;
 - at least one non-floating terminal on a surface of the integrated circuit to mount to a corresponding pad on a substrate, wherein the at least one non-floating terminal comprises a first solder bump and a first conductor;
 - at least one floating terminal on the surface of the integrated circuit to mount to a corresponding pad on the substrate, wherein the at least one floating terminal comprises a second solder bump, a second conductor, and at least one dielectric layer physically separating and in physical contact with the second solder bump and the second conductor; and
 - at least one coupling element to couple any combination of the at least one floating terminal and the at least one non-floating terminal to the node.
2. (Previously Presented) The integrated circuit recited in claim 1 wherein the node is selected from the group consisting of power nodes, ground nodes, and input/output nodes.
3. (Previously Presented) The integrated circuit recited in claim 1 wherein the second solder bump, second conductor, and at least one dielectric layer of the at least one floating terminal form a capacitive element.
4. (Previously Presented) The integrated circuit recited in claim 3 wherein the first conductor and the second conductor can be selectively coupled to the node.

5. (Previously Presented) The integrated circuit recited in claim 4 wherein the substrate pad is selected from the group consisting of a power terminal, a ground terminal, and an input/output terminal.
6. (Previously Presented) The integrated circuit recited in claim 1 wherein the at least one coupling element comprises selector logic coupled to the at least one floating terminal, to the at least one non-floating terminal, and to the node, and comprising at least one control input, at least one logic element coupled to the at least one control input, and at least one output to couple any combination of the first and second conductors to the node.
7. (Previously Presented) An integrated circuit comprising:
a plurality of circuit elements;
a plurality of nodes coupled to the plurality of circuit elements;
a plurality of non-floating terminals on a surface of the integrated circuit;
at least one floating terminal on the surface of the integrated circuit; and
selector logic coupled to the terminals and to the plurality of nodes to couple any combination of the at least one floating terminal and one of the plurality of non-floating terminals to one of the plurality of nodes.
8. (Previously Presented) The integrated circuit recited in claim 7 wherein the one node is selected from the group consisting of power nodes, ground nodes, and input/output nodes.
9. (Previously Presented) The integrated circuit recited in claim 7 wherein the at least one floating terminal comprises a capacitive element.
10. (Previously Presented) The integrated circuit recited in claim 9 wherein the capacitive element comprises a connector element, at least one dielectric layer, and a conductor that can be selectively coupled to the one node.

11. (Previously Presented) The integrated circuit recited in claim 10 wherein the connector element comprises a solder bump.
12. (Previously Presented) The integrated circuit recited in claim 7 wherein the selector logic comprises at least one control input and further comprises at least one output to selectively couple any combination of the at least one floating terminal and one of the plurality of non-floating terminals to the one node.
13. (Previously Presented) An electronic assembly comprising:
an integrated circuit having
 at least one circuit element;
 a node coupled to the at least one circuit element;
 at least one floating terminal on the surface of the integrated circuit to mount to a corresponding pad on a substrate, wherein the at least one floating terminal comprises a solder bump, a conductor, and at least one dielectric layer physically separating and in physical contact with the solder bump and the conductor; and
 at least one coupling element to switchably couple the at least one floating terminal to the node; and
an integrated circuit package substrate comprising a plurality of pads and internal circuit paths, including at least one pad and at least one internal circuit path to couple to the at least one floating terminal.
14. (Previously Presented) The electronic assembly recited in claim 13 wherein the solder bump, conductor, and at least one dielectric layer form a capacitive element.
15. (Previously Presented) The electronic assembly recited in claim 13 wherein the at least one coupling element comprises selector logic coupled to the at least one floating terminal and to the node, and comprising at least one control input, at least one logic element coupled to the at least one control input, and at least one output to couple the conductor of the at least one floating terminal to the node.

16-27. (Canceled)

28. (Original) The integrated circuit recited in claim 1 wherein the at least one circuit element is selected from the group consisting of a digital logic circuit, an analog circuit, a power circuit, a sense circuit, an amplifier circuit, and a radio circuit.

29. (Original) The integrated circuit recited in claim 1 wherein the at least one circuit element comprises an inverter circuit.